

JAPANESE PATENT OFFICE

PATENT JOURNAL

KOKAI PATENT APPLICATION NO. HEI 4[1992]-76946

Int. Cl.⁵: H 01 L 27/00
25/00
25/04
25/065
25/07
25/18
H 01 L 25/04
25/08

Sequence Nos. for Office Use: B 7514-4M
A 7638-4M
7638-4M
7638-4M

Application No.: Hei 2[1990]-189491

Application Date: July 19, 1990

Publication Date: March 11, 1992

No. of Claims: 4 (Total of 6 pages)

Examination Request: Not requested

WAFER INTEGRATED-CIRCUIT DEVICE

Inventor: Tomokazu Yamashita
c/o Fujitsu Ltd.
1015 Kammiotanaka,
Nakahara-ku, Kawasaki-
shi, Kanagawa-ken

Applicant:

Fujitsu Ltd.
1015 Kammiotanaka,
Nakahara-ku, Kawasaki-
shi, Kanagawa-ken

Agents:

Akish Kashiwaya,
patent attorney, and 1
other

[There are no amendments to this patent.]

Claims

1. A wafer integrated-circuit device characterized by the fact that it consists of a wafer (1), in which a circuit (2) for a system is formed, and a wafer (4), in which a circuit (5) having the function of constituting a wafer integrated circuit is formed; with said circuits (2) and (5) of two wafers being mutually connected, so that a system is realized.

2. A wafer integrated-circuit device characterized by the fact that it consists of a wafer (1), in which a circuit (2) for a system is formed, and a wafer (4), in which a circuit (5) having the function of constituting a wafer integrated circuit is formed; with these being laminated on the front and the front, the back and the back, or the front and the back; and with said circuits (2) and (5) of two wafers being mutually connected, so that a system is realized.

3. A wafer integrated-circuit device characterized by the fact that a wafer (1), in which a circuit (2) for a system is formed, and several wafers or chips (4, 10), in which a circuit having the function of constituting a wafer integrated circuit is

formed, are laminated; with these circuits being mutually connected, so that a system is realized.

4. A wafer integrated-circuit device characterized by the fact that a wafer (1), in which a circuit (2) for a system is formed, a wafer (4), in which only wiring is formed, and a chip or wafer (10), in which a circuit having the function of constituting a wafer integrated circuit is formed, are laminated; with these circuits being mutually connected, so that a system is realized.

* * *